

**Date:** October 2019  
**Rev:** VI  
**No. of Components:** Two  
**Mix Ratio by Weight:** 100 : 10  
**Specific Gravity:** Part A: 1.03      Part B: 1.02  
**Pot Life:** 3 Hours  
**Shelf Life- Bulk:** One year at room temperature

**Recommended Cure: 150°C / 1 Hour**

Minimum Alternative Cure(s):  
*May not achieve performance properties listed below*  
 150°C / 1 Minute  
 100°C / 10 Minutes

**NOTES:**

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.

**Product Description:** EPO-TEK® 360ST is a two component, high temperature grade, electrically and thermally insulating epoxy. It is a less thixotropic version of EPO-TEK® 360T.

**Typical Properties:** Cure condition: 150°C / 1 Hour      Different batches, conditions & applications yield differing results.  
 Data below is not guaranteed. To be used as a guide only, not as a specification. \* denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	Part A: Tan	Part B: Amber	
* Consistency:	Slightly thixotropic paste		
* Viscosity (23°C) @ 100 rpm:	1,400 - 2,400	cPs	
Thixotropic Index:	2.6		
* Glass Transition Temp:	≥ 80	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE):			
	Below Tg:	51	x 10 <sup>-6</sup> in/in°C
	Above Tg:	215	x 10 <sup>-6</sup> in/in°C
Shore D Hardness:	85		
Lap Shear @ 23°C:	> 2,000	psi	
Die Shear @ 23°C:	≥ 10	Kg	3,556 psi
Degradation Temp:	344	°C	
Weight Loss:			
	@ 200°C:	0.88	%
	@ 250°C:	1.86	%
	@ 300°C:	4.01	%
Suggested Operating Temperature:	< 275 °C (Intermittent)		
Storage Modulus:	256,460	psi	
* Particle Size:	≤ 20	microns	

ELECTRICAL AND THERMAL PROPERTIES:			
Thermal Conductivity:	N/A		
Volume Resistivity @ 23°C:	≥ 1.8 x 10 <sup>13</sup>	Ohm-cm	
Dielectric Constant (1KHz):	3.58		
Dissipation Factor (1KHz):	0.012		

Epoxyes and Adhesives for Demanding Applications™

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

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**EPO-TEK® 360ST Advantages & Suggested Application Notes:**

- Suitable for fiber optic and circuit assembly applications.
- Recommended for bonding metals, glass, ceramics and many types of plastic.
- High temperature adhesive for hybrids; it can withstand 275°C processing conditions.
- Circuit assembly applications; staking SMD's to PCB, bonding ferrite cores together in copper coil windings and inductor coils and power devices.
- Can be applied by screen printing, spatula, hand held or automatic dispensing equipment.
- Amber color change when properly cured for easy visual ID and inspection.

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